

UNISONIC TECHNOLOGIES CO., LTD

# 2N7002T

**Preliminary** 

**Power MOSFET** 

# 300 mAmps, 60 Volts N-CHANNEL POWER MOSFET

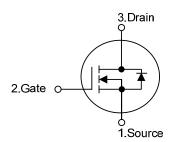
### DESCRIPTION

The UTC **2N7002T** has been designed to minimize on-state resistance while provide rugged, reliable, and fast switching performance. It can be used in most applications requiring up to 400mA DC and can deliver pulsed currents up to 2A. The product is particularly suited for low voltage, low current applications, such as small servo motor control, power MOSFET gate drivers, and other switching applications

#### FEATURES

- \* High Density Cell Design for Low R<sub>DS(ON)</sub>.
- \* Voltage Controlled Small Signal Switch
- \* Rugged and Reliable
- \* High Saturation Current Capability

#### SYMBOL

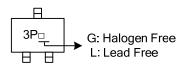


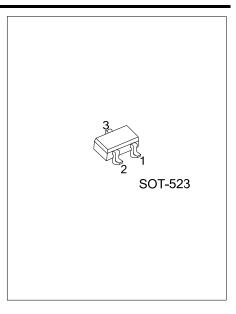
#### ORDERING INFORMATION

Ordering Number		Daakaga	Pin Assignment			Dooking	
Lead Free	Halogen Free	Package	1	2	3	Packing	
2N7002TL-AN3-R	2N7002TG-AN3-R	SOT-523	S	G	D	Tape Reel	

2N7002TG- <u>AN3-R</u>	(1)Packing Type	(1) R: Tape Reel
	(2)Package Type	(2) AN3: SOT-523
	(3)Halogen Free	(3) G: Halogen Free, L: Lead Free

#### MARKING





#### ■ ABSOLUTE MAXIMUM RATINGS (Ta=25°C unless otherwise noted.)

PARAMETER		SYMBOL RATINGS		UNIT
Drain-Source Voltage		V <sub>DSS</sub>	60	V
Drain-Gate Voltage (R <sub>GS</sub> ≤1MΩ)		V <sub>DGR</sub> 60		V
Gate Source Voltage	Continuous	Mara	±20	V
	Non Repetitive(tp<50µs)	V <sub>GSS</sub>	±40	v
Drain Current Continuous I <sub>D</sub>	Continuous	1-	300	mA
	ID	800		
Power Dissipation		D-	200	mW
Derated Above 25°C		PD	1.6	mW/°C
Junction Temperature		TJ	+ 150	°C
Storage Temperature		T <sub>STG</sub>	-55 ~ +150	С°

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.

#### THERMAL CHARACTERISTICS

PARAMETER	SYMBOL	RATINGS	UNIT	
Junction to Ambient	θ <sub>JA</sub>	625 (Note1)	°C/W	

#### ELECTRICAL CHARACTERISTICS (T<sub>A</sub>=25°C, unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =10μA	60			V	
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V			1	μA	
Gate-Source Leakage Current	I <sub>GSSF</sub>	V <sub>GS</sub> =20V, V <sub>DS</sub> =0V			100	nA	
Gale-Source Leakage Current	I <sub>GSSR</sub>	V <sub>GS</sub> =-20V, V <sub>DS</sub> =0V			-100	nA	
ON CHARACTERISTICS (Note2)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{GS} = V_{DS}, I_D = 250 \mu A$	1	2.1	2.5	V	
Drain-Source On-Voltage	M	V <sub>GS</sub> = 10V, I <sub>D</sub> =500mA		0.6	3.75	V	
Drain-Source On-voltage	V <sub>DS (ON)</sub>	V <sub>GS</sub> = 5.0V, I <sub>D</sub> =50mA		0.09	1.5	ľ	
On-State Drain Current	I <sub>D(ON)</sub>	V <sub>GS</sub> =10V,V <sub>DS</sub> ≥2V <sub>DS(ON)</sub>	500	2700		mA	
Static Drain-Source On-Resistance	Deserve	V <sub>GS</sub> =10V, I <sub>D</sub> =500mA,T <sub>J</sub> =125°C			13.5	Ω	
Static Drain-Source On-Resistance	R <sub>DS (ON)</sub>	V <sub>GS</sub> =5.0V, I <sub>D</sub> =50mA			7.5	Ω	
DYNAMIC CHARACTERISTICS							
Input Capacitance	CISS	V <sub>DS</sub> =25V,V <sub>GS</sub> =0V,f=1.0MHz		20	50	pF	
Output Capacitance	Coss			11	25	pF	
Reverse Transfer Capacitance	C <sub>RSS</sub>			4	5	pF	
		$V_{DD}$ =30V, R <sub>L</sub> =150Ω			20	nS	
Turn-On Time	t <sub>on</sub>	I <sub>D</sub> =200mA, V <sub>GS</sub> =10V R <sub>GEN</sub> =25Ω			20		
		V <sub>DD</sub> =30V, R <sub>L</sub> =25Ω		+			
Turn-Off Time	toff	I <sub>D</sub> =200mA, V <sub>GS</sub> =10V			20	nS	
		R <sub>GEN</sub> =25Ω					
DRAIN-SOURCE DIODE CHARACTERIS	TICS AND N	MAXIMUM RATINGS					
Drain-Source Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, Is=115mA (Note)		0.88	1.5	V	
Maximum Pulsed Drain-Source Diode Forward Current	I <sub>SM</sub>				0.8	А	
Maximum Continuous Drain-Source Diode Forward Current	ls				115	mA	

Note: 1. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch. Minimum land pad size.

2. Pulse Test: Pulse Width≤300µs, Duty Cycle≤2.0%



## ■ TEST CIRCUIT AND WAVEFORM

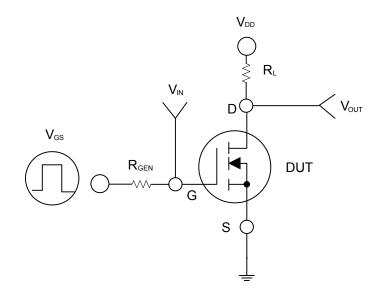


Figure 1

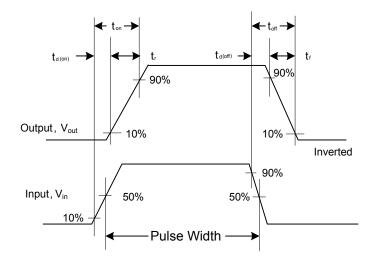


Figure 2. Switching Waveforms

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